

WHAT IS CLAIMED IS:

1. A head suspension of a disk device that supports a head for at least reading a disk medium and comprising:

5 a first connection terminal that electrically connects to said head;

a second connection terminal that connects to external circuits;

third and fourth connection terminals that electrically connect to a head IC, which processes an electrical signal
10 from said head;

a first conductive path that connects said first connection terminal with said third connection terminal;

a second conductive path that connects said second connection terminal with said fourth connection terminal;

15 and

a measurement terminal that is located between said second connection terminal and said fourth connection terminal of said second conductive path, and which is for measuring said head IC.

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2. The head suspension of claim 1 wherein;

said measurement terminal and said first connection terminal are located such that they are on the same plane of said suspension.

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3. The head suspension of claim 1 wherein;

said first, second, third and fourth connection

terminals, said first and second conductive paths, and said measurement terminal are formed using a thin-film pattern on the base of said suspension.

- 5 4. The head suspension of claim 1 further comprising:
 a base for said head suspension; and
 a flexible cable on which said first, second, third and fourth connection terminal, said first and second conductive paths and said measurement terminal are formed.

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5. The head suspension of claim 1 wherein said first connection terminal is electrically connected to a magnetic head.

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6. A disk device comprising:
 a head for at least reading a disk medium;
 a head IC that processes an electrical signal from said head;
 a head suspension which supports said head and which
20 contains said head IC; and
 an actuator that supports said head suspension and moves
 said head with respect to said disk medium; wherein
 said head suspension comprises:
 a first connection terminal for electrically connecting
25 to said head;
 a second connection terminal for connecting to external
 circuits;

third and fourth connection terminals for electrically connecting to said head IC;

a first conductive path that connects said first and third connection terminals;

5 a second conductive path that connects said second and fourth connection terminals; and

a measurement terminal that is located between said second connection terminal and said fourth connection terminal of said second conductive path, and which is for
10 measuring said head IC.

7. The disk device of claim 6 wherein;

said measurement terminal and said first connection terminal are located such that they are on the same plane
15 of said suspension.

8. The disk device of claim 6 wherein;

said first, second, third and fourth connection terminals, said first and second conductive paths, and said
20 measurement terminal are formed using a thin-film pattern on the base of said suspension.

9. The disk device of claim 6 further comprising:

a base for said head suspension; and

25 a flexible cable on which said first, second, third and fourth connection terminal, said first and second conductive paths and said measurement terminal are formed.

10. The disk device of claim 6 wherein said head comprises a magnetic head.

5 11. A testing method for a head IC comprising:
 a step of installing a head IC for processing an electric signal from a head for at least reading a disk medium, on a head suspension that supports said head; and
 a step of placing a probe on a terminal of said head
10 suspension to check electric characteristics of said head IC.

12. The testing method of claim 11 wherein said head suspension comprises:

15 a first connection terminal for electrically connecting to said head;
 [†] a second connection terminal for connecting to external circuits;
 third and fourth connection terminals for electrically
20 connecting to said head IC;
 a first conductive path that connects said first and third connection terminals;
 a second conductive path that connects said second and fourth connection terminals; and
25 a measurement terminal that is located between said second connection terminal and said fourth connection terminal of said second conductive path, and which is placed

said probe.

13. The testing method of claim 11 wherein;
said measurement terminal and said first connection
5 terminal are located such that they are on the same plane
of said suspension.

14. The testing method of claim 11 wherein;
said first, second, third and fourth connection
10 terminals, said first and second conductive paths, and said
measurement terminal are formed using a thin-film pattern
on the base of said suspension.

15. The testing method of claim 11 further comprising:
15 a base for said head suspension; and
a flexible cable on which said first, second, third and
fourth connection terminal, said first and second conductive
paths and said measurement terminal are formed.

20 16. The testing method of claim 11 wherein said head
comprises a magnetic head.

17. A manufacturing method for a HGA comprising:
a step of installing a head IC for processing an electric
25 signal from a head for at least reading a disk medium, on
a head suspension that supports said head;
a step of placing a probe on a terminal of said head

suspension to check electric characteristics of said head
IC; and

a step of installing a head on said head suspension
with said head IC.